METAL FILM



MF Coat-Insulated Fixed Metal Film Resistors



Coating color : Light gray Marking : Color code

Features

- High precision and low T.C.R. metal film resistors.
- Automatic insertion is applicable.
- Various formings are available.
- Excellent stability for a long time.
- Products meet EU-RoHS requirements.
- \bullet AEC-Q200 Tested (Exemption MF1/2).

Reference Standards

IEC 60115-1					
JIS C 5201-1					
EIAJ RC-2137					



Dimensions

Turno		Dimensions (mm)									
Туре	L	C Max.	D	d (Nominal)	l ±3 ^{≈1}	(1000pcs)					
MFS1/4	3.2±0.2	3.4	1.7 ^{+0.2}	0.45		120					
MF1/4	0.0+0.5	7.1	0.0+0.0		28	215					
MFS1/2	6.3±0.5	7.1	2.3±0.3	0.6	28	215					
MF1/2	9.0±1.0	11.1	3.5±0.4			360					

%1 Lead length changes depending on taping and forming type.

Type Designation

Example

MF Product Code	1/4 Power Rating S1/4:0.25W	D T.C.R. (×10 ⁻⁶ /K) C:±50 D:±100	C Terminal Surface Material C : SnCu	T52 Taping & Forming See table	A Packaging A: AMMO P · PEEL	1002 Nominal Resistance D, F : 4 digits	F Resistance Tolerance D:±0.5% E:±1%
	1/4:0.25W	D:±100		below	R:REEL	G:3 digits	F:±1%
	S1/2:0.5W	L:±200			Nil: BOX		G:±2%
	1/2:05W						

Contact us when you have control request for environmental hazardous material other than the substance specified by EU-RoHS.

For further information on taping and forming, please refer to APPENDIX C on the back pages.

Taping & Forming Matrix

Turne	Axial 7	Faping		Radial Taping			U Forming			M Forming		
Туре	T26	T52	VT	VTP	VTE	MT	U	N	15	M10	M12.5	M15
MFS1/4C	0	0	0	-	-	0	0	M5F	M5R	-	-	-
MF1/4C	0	0	0	0	0	-	0	_	-	M10F	M12.5R	-
MFS1/2C	0	0	0	0	0	-	-	—	-	M10R	—	-
MF1/2C	—	0	—	-	—	-	-	—	—	—	M12.5R	M15R

\Box : T.C.R.

Ratings

Туре	Power T.C.R.		Resistance Range (Ω)			Max. Working	Max. Overload Voltage	Dielectri Withstanding Voltage	Taping & Q'ty/AMMO (pcs)	
туре	Rating	(×10 ⁻⁶ /K)	$ \begin{array}{ c c c c c c c c } \hline D:\pm 0.5\% & F:\pm 1\% & G:\pm 2\% \\ \hline E24\cdot E192 & E24\cdot E96 & E24 \\ \hline \end{array} \\ \hline \end{array} \\ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	T26A	T52A					
MFS1/4CC	0.25W	C:±50	49.9~562k	10~1M				300V	3,000	3,000
MFS1/4DC	0.25	D:±100	49.9~56∠k	10~110	_			3000	3,000	3,000
MF1/4CC		C:±50	10~2.21M	10~2.21M		250V	500V		2,000	2,000
MF1/4DC	0.25W	D:±100	10~2.211	10~2.2110	_				2,000	2,000
MF1/4LC		L:±200	-	1.0~10	0.51~10			500V	2,000	2,000
MFS1/2CC		C:±50	10.114	10.004	10~2.2M				2,000	2,000
MFS1/2DC	0.5W	D:±100	10~1M	M 10~2.2M	2.2101 10~2.2101				2,000	2,000
MF1/2CC		C:±50	10. 5.05M	10~4.99M		350V	700V			2,000
MF1/2DC	0.5W	D:±100	10~5.05M	10~5.11M				700V	_	2,000
MF1/2LC		L:±200	-	1.0~10	0.51~10					2,000

Rated Ambient Temperature :+70°C

Operating Temperature Range $:\!-55^\circ\!\mathrm{C}\!\sim\!+155^\circ\!\mathrm{C}$

 $Rated \ voltage = \sqrt{Power \ Rating \times Resistance \ value} \ or \ Max. \ working \ voltage, \ whichever \ is \ lower.$



Derating Curve



For resistors operated at an ambient temperature of 70 $\!\!\!^\circ C$ or higher, the power shall be derated in accordance with the above derating curve.

Performance

Test Items	Performance Requirements $\Delta R \pm (\% + 0.05 \Omega)$		Test Methods				
	Limit	Typical					
Resistance	Within specified tolerance	-	25°C				
T.C.R.	Within specified T.C.R.	—	+25℃/+125℃				
Overload (Short time)	0.5	0.3	Rated voltage ×2.5 or Max. overload vol., whichever is lower, for 5s : MFS1/4, MF1/4, MF1/2 Rated voltage ×2 or Max. overload vol., whichever is lower, for 5s : MFS1/2				
Resistance to soldering heat	0.75 : MFS1/4 0.5 : MF1/4, MFS1/2, MF1/2	0.4 : MFS1/4 0.25 : MF1/4, MFS1/2, MF1/2	260°C±5°C, 10s±1s				
Rapid change of temperature	1.0	0.3	-55°C (30min.) /+155°C (30min.) 5 cycles				
Moisture resistance	1.5 : MFS1/4 1 : MF1/4, MFS1/2, MF1/2	1 : MFS1/4 0.75 : MF1/4, MFS1/2, MF1/2	40°C±2°C, 90%~95%RH, 1000h 1.5h ON/0.5h OFF cycle				
Endurance at 70°C	1.5 : MFS1/4 1 : MF1/4, MFS1/2, MF1/2	1 : MFS1/4 0.75 : MF1/4, MFS1/2, MF1/2	70°C±2°C, 1000h 1.5h ON/0.5h OFF cycle				

Precautions for Use

• Ionic impurities such as flux etc. that are attached to these products or those mounted onto a PCB, negatively affect their moisture resistance, corrosion resistance, etc. The flux may contain ionic substances like chlorine, acid, etc. Please wash them to get rid of these ionic substances especially when using lead-free solder that may contain much of the said substances for improving a wetting characteristic. Using RMA solder or RMA flux, or well-washing is needed. Also, attaching ionic substances such as perspiration, salt etc. by storage environments or mounting conditions/environments negatively affects their moisture resistance, corrosion resistance etc. Please wash them to remove the ionic substances when they are polluted.